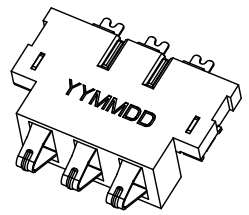
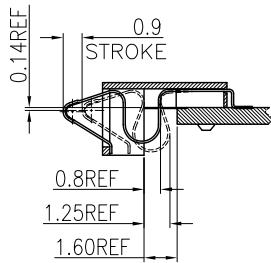
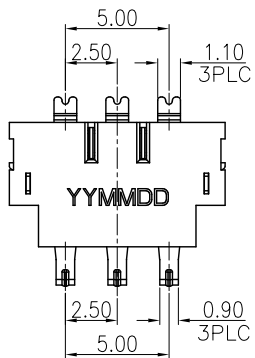


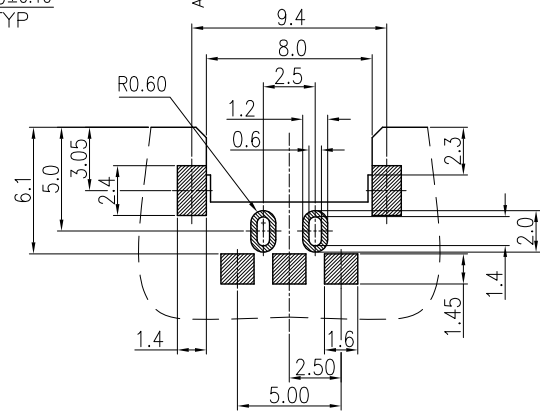
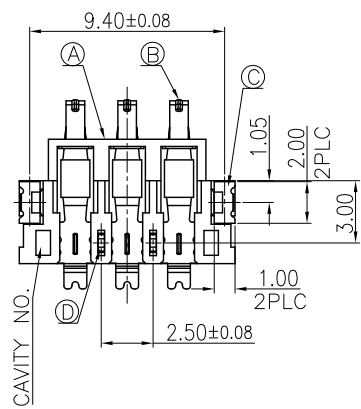
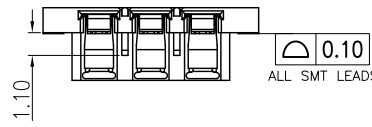
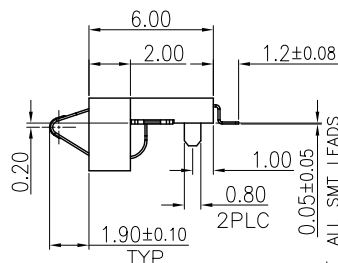
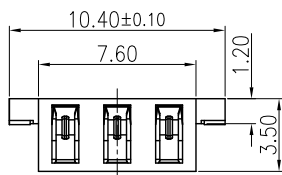
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	Chunxiao	2014.01.21



WORKING STATION SIMULATION

NOTE:

- MATERIAL:  
HOUSING: HIGE TEMP. THERMOPLASTIC, UL94-V0(HF), COLOR BLACK.  
CONTACT: COPPER ALLOY, T=0.10;  
TAB: COPPER ALLOY, T=0.20.  
HOOK: COPPER ALLOY, T=0.30
- FINISH:  
CONTACT:  
15u" MIN GOLD PLATING ON CONTACT AREA;  
1u" MIN GOLD PLATING ON SOLDER TAILS;  
50u"~180u" NICKEL UNDERPLATING OVERALL.  
TAB&HOOK:  
40u"~50u" HIGH TEMP. TIN PLATING ALL OVER;  
20u"~30u" NICKEL UNDERPLATING OVERALL
- SPECIFICATION: SEE "2.5mm PITCH BATTERY 3PIN 4.5H PRODUCT SPEC."
- SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
- TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK : Ⓢ
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PACKAGING : TAPE & REEL.



RECOMMENDED PC. BOARD LAYOUT  
(TOL. ±0.05)(TOP VIEW)

D	HOOK	2	COPPER ALLOY, 0.20T	Sn 40~50u", Ni 20~30u"
C	TAB	2	COPPER ALLOY, 0.30T	Sn 40~50u", Ni 20~30u"
B	CONTACT	3	COPPER ALLOY, 0.10T	Au15u" MIN, Ni 50~180u"
A	HOUSING	1	HI-TEMP THERMOPLASTIC, UL94-V0(HF)	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES			Singatron Enterprise Co., Ltd. 信音企业股份有限公司	
DECIMALS:		ANGLES:		TITLE
X	:±0.5	X	:±2°	2.5mm PITCH BATTERY 3PIN 1.2HEIGHT
X.X	:±0.3	X.X	:±1°	DWN Chunxiao 14/1/24 PART NO. 2BA2002-001521F
X.XX	:±0.2			CHKD Winkan 14/1/24 SCALE 4:1 UNIT: mm
				APVD Liao 14/1/24 SIZE: A3 SHEET: 10F1 REV: A
CUSTOMER COPY				